SCLS513B - JULY 2003 - REVISED FEBRUARY 2008

- Qualified for Automotive Applications
- ESD Protection Exceeds 1000 V Per MIL-STD-883, Method 3015; Exceeds 100 V Using Machine Model (C = 200 pF, R = 0); Exceeds 2000 V Charged Device Model
- Single Supply or Dual Supplies
- Wide Range of Supply Voltage ... 2 V to 36 V
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.8 mA Typ
- Low Input Bias Current . . . 25 nA Typ
- Low Input Offset Current . . . 5 nA Typ
- Low Input Offset Voltage . . . 2 mV Typ
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS

D PACKAGE (TOP VIEW) 10UT [14 NOUT3 20UT 1 2 13 OUT4 V_{CC} [] з 12 GND 2IN- **1** 4 11 **∏** 4IN+ 2IN+ **1** 5 1IN- 6 1IN+ 7 8 3IN−

description/ordering information

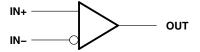
This device consists of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

ORDERING INFORMATION†

T _A	PAC	KAGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 125°C	SOP – D	Tape and reel	LM239AQDRQ1§	LM239AQ1	

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

symbol (each comparator)





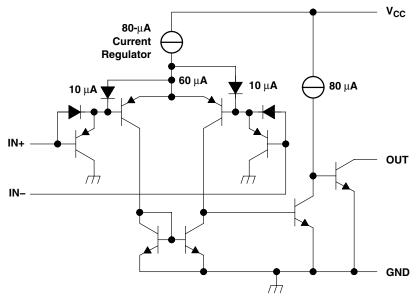
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

[§] This package is only available taped and reeled, with standard quantities of 2500 pieces per reel.

schematic (each comparator)



All current values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	36 V
Differential input voltage, V _{ID} (see Note 2)	
Input voltage range, V _I (either input)	0.3 V to 36 V
Output voltage, V _O	36 V
Output current, I _O	20 mA
Duration of output short circuit to ground (see Note 3)	Unlimited
Package thermal impedance, θ_{JA} (see Note 4)	86°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Maximum operating junction temperature, T _J	136°C
Storage temperature range, T _{stq}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-7.



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electrical characteristics at specified free-air temperature, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST CONDITI	T _A ‡	MIN	TYP	MAX	UNIT		
V loost effect valtage		$V_{CC} = 5 \text{ V to } 30 \text{ V}, V_{IC} = V_{ICR}(\text{min}),$		25°C		1	2.5	.,	
V_{IO}	Input offset voltage	$V_0 = 1.4 \text{ V}$		Full range			5.5	mV	
		V 44V		25°C		5	50		
l _{IO}	Input offset current	V _O = 1.4 V	/ _O = 1.4 V				150	nA	
				25°C		-25	-250		
I _{IB}	Input bias current	V _O = 1.4 V	Full range			-400	nA		
	0			25°C	0 to V _{CC} -1.5				
V _{ICR}	Common-mode input-voltage range			Full range	0 to V _{CC} -2			V	
A _{VD}	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_{O} = 1.4 V to 11.4 V, R _L \geq 15 k Ω to V_{CC}		25°C	50	200		V/mV	
	Library Laurent australia australia	V 4V	V _{OH} = 5 V	25°C		0.1	50	nA	
Іон	High-level output current	V _{ID} = 1 V	V _{OH} = 30 V	Full range			1	μΑ	
.,		V 4V		25°C		150	400	.,	
V _{OL}	Low-level output voltage	$V_{ID} = -1 V$, $I_{OL} = 4 \text{ mA}$		Full range			700	mV	
I _{OL}	Low-level output current	$V_{ID} = -1 V$,	V _{OL} = 1.5 V	25°C	6	16		mA	
Icc	Supply current (four comparators)	$V_{O} = 2.5 \text{ V},$	No load	25°C		8.0	2	mA	

[†] All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CON	MIN	TYP	MAX	UNIT	
Response time	R _L connected to 5 V through 5.1 kΩ,	100-mV input step with 5-mV overdrive	1.3			
	C _L = 15 pF [§] , See Note 5	TTL-level input step		0.3		μs

[§] C_L includes probe and jig capacitance.

NOTE 5: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

[‡] Full range (MIN to MAX) for LM239AQ is -40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.



PACKAGE OPTION ADDENDUM

25-Sep-2019

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	_		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM239AQDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM239AQ1	Samples
LM239AQDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM239AQ1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

25-Sep-2019

OTHER QUALIFIED VERSIONS OF LM239A-Q1:

www.ti.com

● Enhanced Product: LM239A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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